

ABSTRACT OF THE INVENTION

The present invention provides a plurality of vertically stacked semiconductor dies which are electrically connected to each other. Each semiconductor die has leads which extend out from at least two opposed side surfaces of the semiconductor die. Each lead defines a first junction, a second junction, an inner width and an outer width. The second junctions of the leads of the upper semiconductor die are electrically connected to the first junctions of the leads of the lower semiconductor die. Additionally, the inner widths of the leads of the upper semiconductor die prior to electrically connecting the leads of the upper and lower semiconductor dies are less than the outer widths of the leads of the lower semiconductor die.